

Amendments to the Specification

Please replace the paragraph beginning on page 3, line 9 with the following amended paragraph:

The object of the invention is achieved by a first semiconductor device having bump electrodes electrically connected to connection pads formed on a semiconductor chip, tips of the bump electrodes ~~exposing~~ being exposed at a surface of a sealing resin film formed on a surface of the semiconductor chip, wherein

Please replace the paragraph beginning on page 3, line 21 with the following amended paragraph:

The object of the invention is also achieved by a second semiconductor device having bump electrodes electrically connected to connection pads formed on a semiconductor chip, tips of the bump electrodes ~~exposing~~ being exposed at a surface of a sealing resin film formed on a surface of the semiconductor chip,